



FIG. 2

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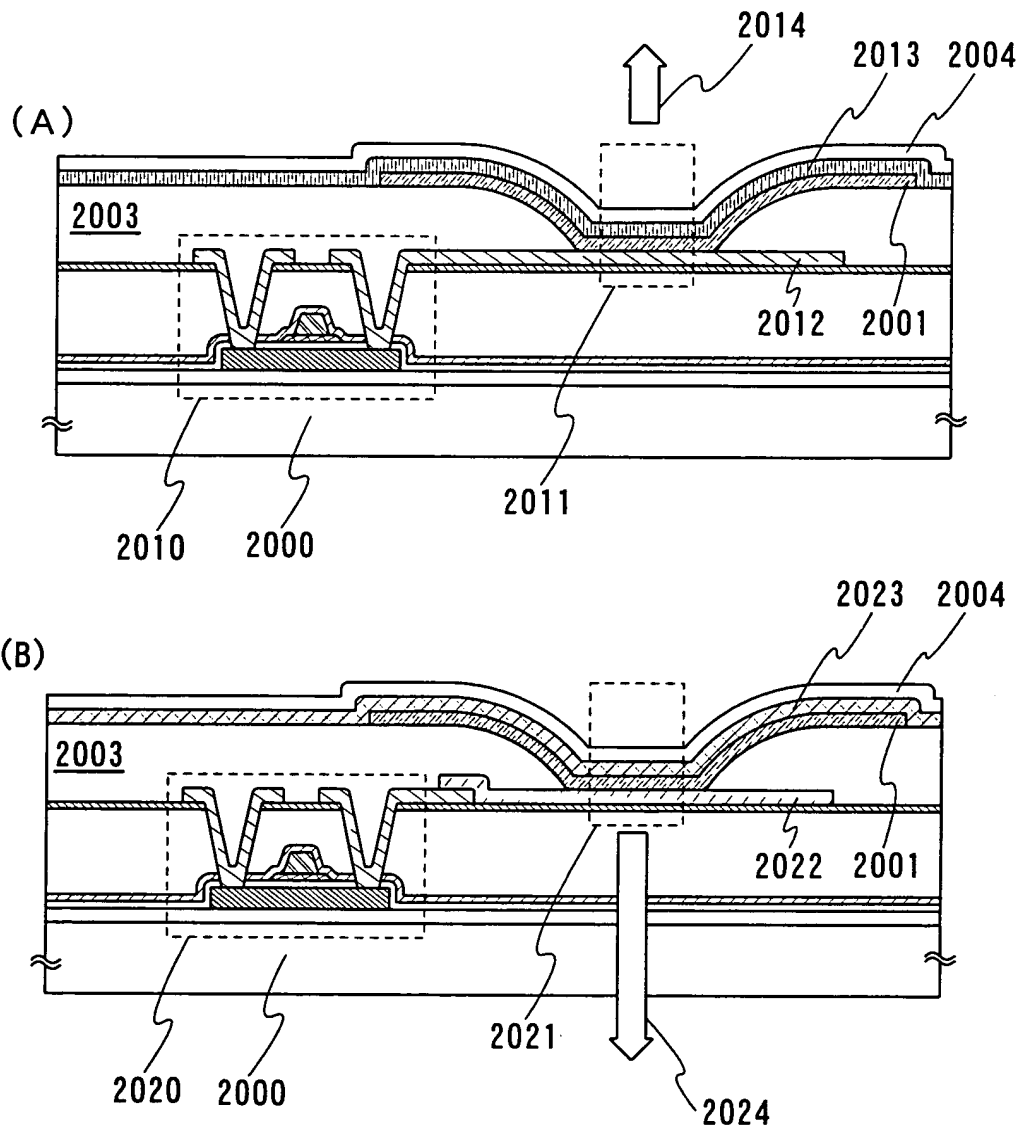
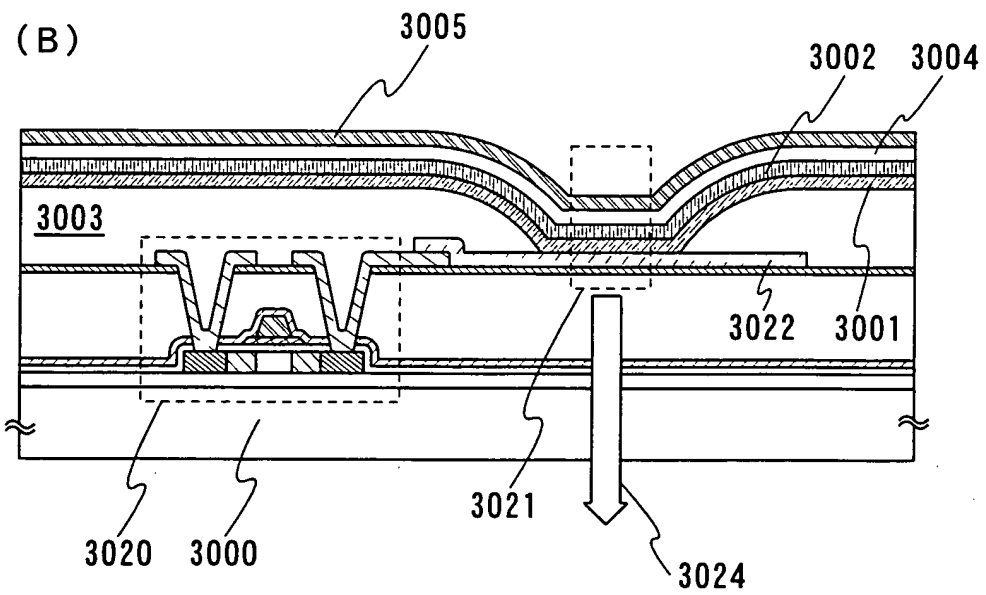
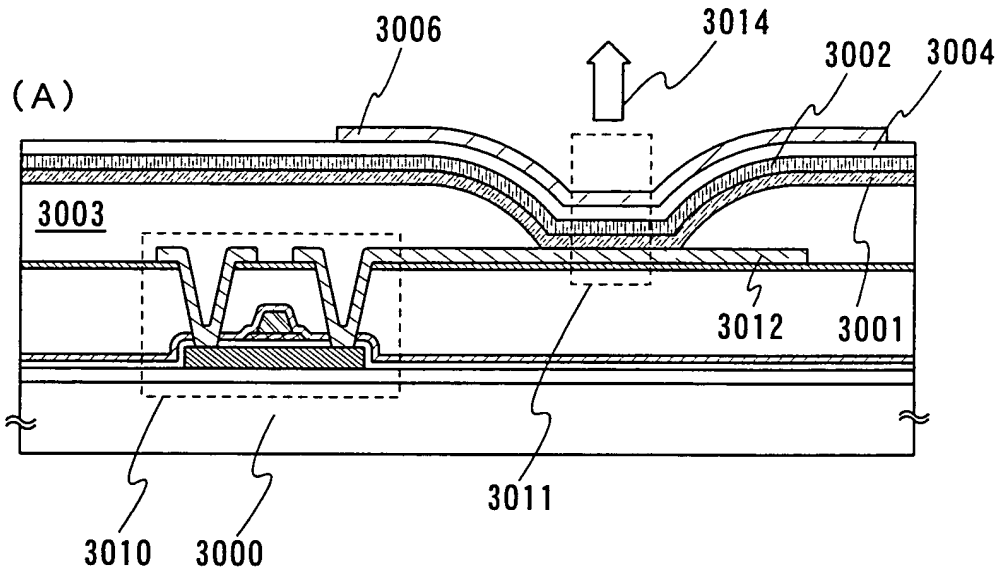


FIG. 3

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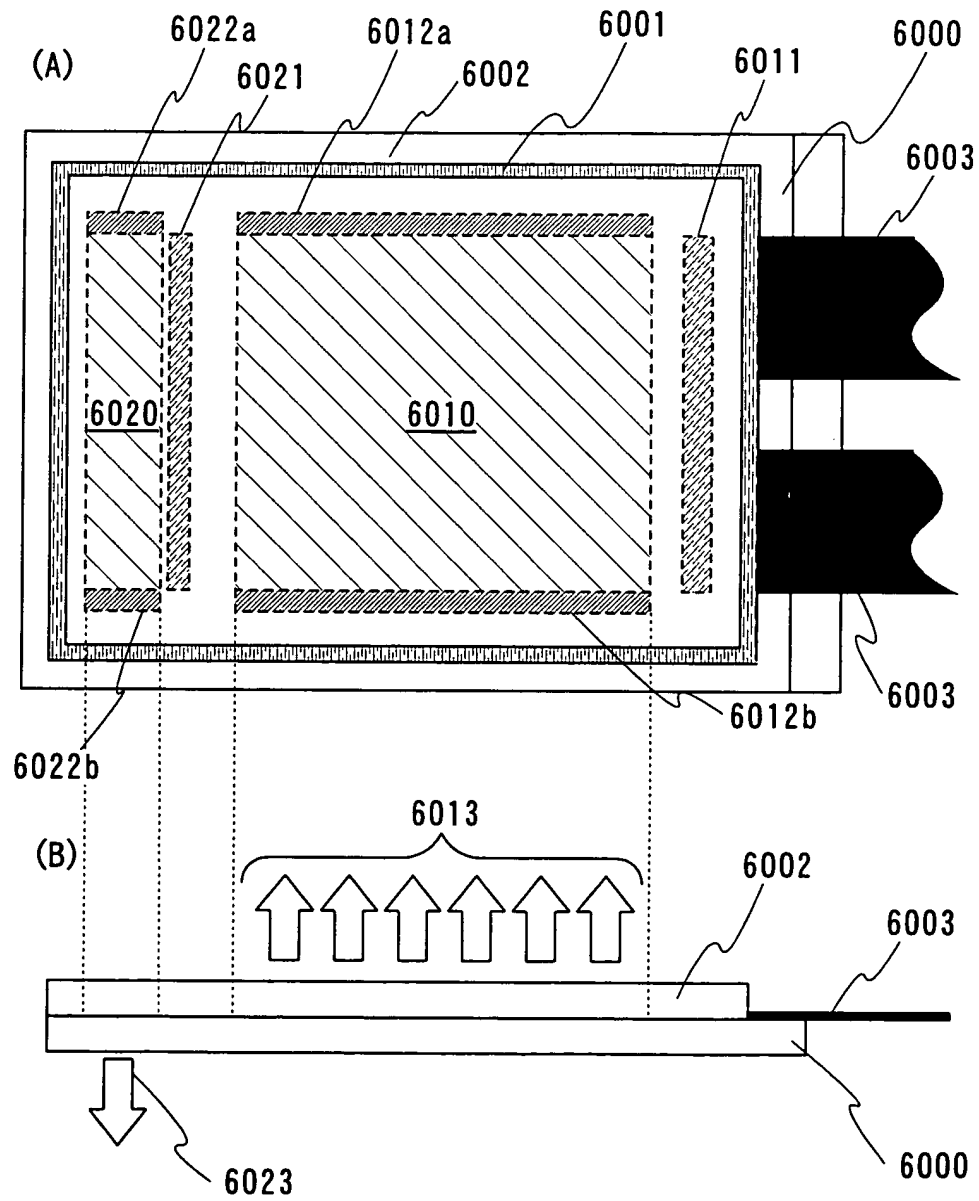
(A) This cross-sectional view shows a semiconductor device with a substrate 4015 and a base layer 4011. A patterned layer 4001 is on top of 4011, with a recessed region 4012. A layer 4003 is on top of 4001. A dashed box indicates a region where a layer 4014 is being removed, as shown by an upward arrow. Other layers include 4000, 4010, 4002, and 4004.

(B) This cross-sectional view shows the same device after a process step. A new layer 4025 has been added on top of 4003. A dashed box indicates a region where a layer 4022 is being removed, as shown by a downward arrow 4024. Other layers include 4020, 4000, 4021, 4002, and 4004.



FIG. 6

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FIG. 7

